Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2576	(@ad<"20010110") and (wafer with (cap or lid))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 09:57
L2	271	(@ad<"20010110") and (wafer near (cap or lid))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 08:10
L3	33	("5798557").URPN.	USPAT	OR	OFF	2005/05/13 08:39
L4	0	("6878564").URPN.	USPAT	OR	OFF	2005/05/13 08:40
L5	14	("20020117623" | "4742432" | "4889587" | "5230759" | "5500540" | "5656776" | "5798557" | "5805757" | "5824177" | "5915168" | "5923995" | "5953355" | "6001664" | "6365920").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/05/13 08:40
L6	18958	(@ad<"20010110") and ((chip or die or wafer) with (sink or spreader or cap or lid))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 10:10
L7	3261	L6 and (mold or molding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 09:24
L8	1695	L7 and (recess or cavity)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 09:25
L9	297	L8 and release	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 09:25

L10	564364	"427"/$.ccls. or "264"/$.ccls. or 272/ccls. or "156"/$.ccls. or "106"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 09:49
L11	254	L10 and (@ad<"20010110") and (wafer with (sink or spreader or cap or lid))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 09:53
L12	245	L11 not L2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 09:53
L13	238	L12 not L9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 09:53
L14	1147	(@ad<"20010110") and ((wafer or chip or die) near (cap or lid))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 09:57
L15	271	(@ad<"20010110") and (wafer near (cap or lid))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 09:58
L16	27	L15 and (encapsulant or encapsulate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 09:58
L17	47	L15 and (encapsulant or encapsulate or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 10:00
L18	1	("6828674").PN.	USPAT	OR	OFF	2005/05/13 10:08
L19	1	("6350113").PN.	USPAT	OR	OFF	2005/05/13 10:08

L20	39015	(@ad<"20010110") and ((chip or die or wafer) with (cover or sink or spreader or cap or lid))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 10:10
L21	835345	L20 1and (((top or lower or first) and (bottom or lower or second)) with (mold or dice or base))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 10:12
L22	6093	L20 and (((top or lower or first) and (bottom or lower or second)) with (mold$3 or dice or base))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 10:14
L23	407	L1 and l22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 10:14
L24	373	L23 not L2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 10:13
L25	369	L24 not L9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 10:13
L26	303	L25 not L13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 10:13
L27	7660	L20 and (((top or lower or first) and (bottom or lower or second)) with (chamber or mold$3 or dice or base))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 10:14

L28	698	L1 and I27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 10:14